

FORM PTO-1449(Modified)

ATTY. DOCKET NO. H0498.70114US01

SERIAL NO. 10/677,103

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S
INFORMATION DISCLOSURE STATEMENT

APPLICANT Enoch Kim et al.

FILING DATE 10/01/2003

GROUP ART UNIT: 1732

U.S. PATENT DOCUMENTS

Exam Init	Ref Des	Document No.	Date	Name	Class	Sub Class	FILING DATE If Appropriate
MOV	*	3,873,359	03/25/75	Lando			
A	*	3,873,360	03/25/75	Lando	1		
	*	3,900,614	08/19/75	Lando			
	*	4,098,922	07/04/78	Dinella et al.			
	*	4,100,037	07/11/78	Baron et al.			
	*	4,192,764	07/11/80	Madsen			
	*	4,258,001	03/24/81	Pierce et al.			
	*	4,322,457	03/30/82	Baron et al.			
	*	4,472,458	09/18/84	Sirinyan et al.			
	*	4,508,755	04/02/85	Reintjes et al.			
	*	4,555,414	11/26/85	Hoover et al.			
	*	4,637,904	01/87	Rounds			
	*	4,690,715	09/01/87	Allara et al.			
	*	4,710,401	12/87	Warren Jr. et al.			
	*	4,728,591	03/01/88	Clark et al.			
	*	4,802,951	02/07/89	Clark et al.			
	*	4,869,778	09/89	Cote			
	*	4,959,252	09/25/90	Bonnebat et al.			
	*	5,073,495	12/17/91	Anderson			
	*	5,079,600	01/07/92	Schnur et al.			
	*	5,087,510	02/11/92	Tokas et al.			
	*	5,141,785	08/25/92	Yoshinada et al.			
	*	5,170,461	12/08/92	Yoon et al.			
	*	5,227,474	07/13/93	Johnson			
	*	5,259,926	11/09/93	Kuwabara et al.			
	*	5,345,869	09/13/94	Treverton et al.			
	*	5,385,116	01/31/95	Hattori et al.			
	*	5,439,829	08/08/95	Anderson et al.			
	*	5,471,455	11/28/95	Jabr			
	*	5,484,324	01/16/96	Okabayashi et al.			
	*	5,512,131	04/30/96	Kumar et al.			
	*	5,534,101	07/09/96	Keyworth et al.			
	*	5,620,850	04/15/97	Bamdad et al.			
MOV	*	5,976,826	11/02/99	Singhvi et al.			

* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. _____, filed _____, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

Examiner

M. Vung

DATE CONSIDERED

12/22/06

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.

FORM PTO-1449(Modified)

JUN 04 2004

ATTY. DOCKET NO. H0498.70114US01

SERIAL NO. 10/677,103

LIST OF PATENTS AND PUBLICATIONS FOR APPLICATION
INFORMATION DISCLOSURE STATEMENT

APPLICANTS: Enoch Kim et al.

FILING DATE 10/01/2003

GROUP ART UNIT: 1732

U.S. PATENT DOCUMENTS

Exam Init	Ref Des	Document No.	Date	Name	Class	Sub Class	FILING DATE If Appropriate
MDV	*	5,989,835	11/23/99	Dunlay et al.			
	*	6,103,479	08/15/00	Taylor			
		6,355,198	03/12/02	Kim et al.			
		6,660,192	12/09/03	Kim et al.			
MDV		2002-0066978	06/06/02	Kim et al.			

FOREIGN PATENT DOCUMENTS

		Country & Doc. No. (11)	Pub. Date (43)		Class	Sub Class	Translation Yes No
MDV	*	EP 0112721	07/04/84	Comtech Research Unit Limited			
	*	EP 0672765 A1	09/20/95	Studiengesellschaft Kohle mbH			
	*	JP 07237229	02/25/94	Canon Inc.			
	*	JP 2165933	06/26/90	Motoyuki			
	*	WO 96/29629	09/26/96	Whitesides et al.			
	*	WO 97/07429	02/27/97	Clem et al.			
MDV	*	WO 97/33737	09/18/97	Enoch Kim et al.			

OTHER ART

(Including Author, Title, Date, Pertinent Pages, Publication, Etc.)

MDV	*	P.M. St. John et al., "Microcontact printing and pattern transfer using trichlorosilanes on oxide substrates," <i>Appl. Phys. Lett.</i> , Vol. 68, No. 7, pp. 1022-24, February 12, 1996.
	*	E. Kim et al., "Two-and Three-Dimensional Crystallization of Polymeric Microspheres by Micromolding in Capillaries," <i>Advanced Materials</i> , Vol. 8, No. 3, pp. 245-47, March 1, 1996.
	*	E. Kim et al., "Combining Patterned Self-Assembled Monolayers of Alkanethiolates on Gold with Anisotropic Etching of Silicon to Generate Controlled Surface Morphologies," <i>J. Electrochem. Soc.</i> , Vol. 142, No. 2, pp. 628-33, February 1995.
	*	T.P. Moffat et al., "Patterned Metal Electrodeposition Using an Alkanethiolate Mask," <i>J. Electrochem. Soc.</i> , Vol. 142, No. 11, November 1995.
	*	E.A. Dobisz et al., "Self-Assembled Monolayer Films for Nanofabrication," <i>Mat. Res. Soc. Symp. Proc.</i> , Vol. 380, 1995.
	*	J.K. Schoer et al., "Scanning Probe Lithography," <i>Langmuir</i> , Vol. 10, No. 3, pp. 617-18, 1994.
	*	H.C. Haverkorn van Rijsewijk, et al., "Manufacture of LaserVision video discs by a photopolymerization process," <i>Philips Technical Review</i> , Vol. 40, No. 10 (1982), pp. 287-97.
	*	M. Emmelius et al., "Materials for Optical Data Storage," <i>Ignew. Chem. Int. Ed. Engl.</i> 28, Vol. 28, No. 11, (1989), pp. 1445-1600.
	*	F. Lenzman et al., "Thin-Film Micropatterning Using Polymer Microspheres," <i>Chem. Mater.</i> , Vol. 6, (1994), pp. 156-59.
	*	S. Chou et al., "Imprint of sub-25 nm vias and trenches in polymers," <i>Appl. Phys. Lett.</i> 67 (21), 1995, pp. 3114-6.
	*	C.D. Dushkin et al., "Colored Multilayers from Transparent Submicrometer Spheres," <i>Langmuir</i> , Vol. 9 (1993), pp. 3695-3701.
MDV	*	S. Hayashi et al., "Imaging by Polystyrene Latex Particles," <i>Journal of Colloid & Interface Science</i> , Vol. 144, No. 2 (1991), pp. 538-47.

* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. _____, filed _____, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

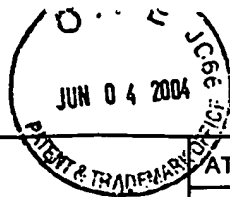
Examiner

M. Vargot

DATE CONSIDERED

12/22/06

EXAMINER: Initial 1 reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.



FORM PTO-1449(Modified)

ATTY. DOCKET NO. H0498.70114US01

SERIAL NO. 10/677,103

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S
INFORMATION DISCLOSURE STATEMENT

APPLICANTS: Enoch Kim et al.

FILING DATE 10/01/2003

GROUP ART UNIT: 1732

OTHER ART

(Including Author, Title, Date, Pertinent Pages, Publication, Etc.)

NOV	*	Y. Xia et al., "Microcontact Printing of Octadecylsiloxane on the Surface of Silicon Dioxide and its Application in Microfabrication," <i>J. Am. Chem. Soc.</i> , Vol. 117, No. 37 (1995), pp. 9576-9577.
	*	J.F. Dijkstra, "Analysis of the injection-molding process," <i>Philips Tech. Rev.</i> 44, No. 7, (1989), pp. 212-217.
	*	J. Shaw, "Capillary fill encapsulation of ISFETs," <i>Sensors and Actuators A</i> , 37-38, (1993), pp. 74-76.
	*	J. Jacobs et al., "Combinatorial chemistry - applications of light-directed chemical synthesis," <i>Tibtech</i> , Vol. 12 (1994), pp. 19-26.
	*	S. Sundberg et al., "Spatially-Addressable Immobilization of Macromolecules on Solid Supports," <i>J. Am. Chem. Soc.</i> , Vol. 117 (1995), pp. 12050-12057.
	*	C. Gorman et al., "Fabrication of Patterned, Electrically Conducting Polypyrrole Using a Self-Assembled Monolayer: A Route to All-Organic Circuits," <i>Chem. Mater.</i> 7, (1995), pp. 526-629.
	*	J. Wilbur et al., "Microfabrication by Microcontact Printing of Self-Assembled Monolayers," <i>Adv. Mater.</i> 6, No. 7/8, (1994), pp. 600-04.
	*	E. Kim et al., "Polymer microstructures formed by moulding in capillaries," <i>Nature</i> , Vol. 376, (1995) pp. 581-84.
	*	A. Kumar et al., "Patterning Self-Assembled Monolayers: Applications in Material Science," <i>Langmuir</i> , 10, (1994) pp. 1498-1511.
	*	D. Pritchard et al., "Micron-Scale Patterning of Biological Molecules," <i>Angew. Chem. Int. Ed. Engl.</i> 34, No. 1 (1995), pp. 91-3.
	*	S. Potochnik et al., "Selective Copper Chemical Vapor Deposition Using Pd-Activated Organosilane Films," <i>Langmuir</i> , Vol. 11, No. 6, (1995), pp. 1841-1845.
	*	W. Dressick et al., "Patterning of Self-Assembled Films Using Lithographic Exposure Tools," <i>Jpn. J. Appl. Phys.</i> , Vol. 32 (1993), pp. 5829-5839.
	*	G. Lazarov et al., "Formation of Two-dimensional Structures from Colloidal Particles on Fluorinated Oil Substrate," <i>J. Chem. Soc. Faraday Trans. 90</i> (14), (1994), pp. 2077-2083.
	*	P. Hoyer et al., "Small quantum-sized CdS particles assembled to form a regularly nanostructured porous film," <i>Appl. Phys. Lett.</i> 66 (20) (1995), pp. 2700-02.
	*	H. Bonnemenn et al., "Preparation and Catalytic Properties of NR+4-Stabilized Palladium Colloids," <i>Applied Organometallic Chemistry</i> , Vol. 8 (1994), pp. 361-378.
	*	K. Nagayami, "Fabrication of Two-Dimensional Colloidal Arrays," <i>Phase Transitions</i> , Vol. 45, (1993), pp. 185-203.
	*	M. Reetz et al., "Size-Selective Synthesis of Nanostructured Transition Metal Clusters," <i>J. Am. Chem. Soc.</i> 116 (1994), pp. 7401-7402.
	*	M. Reetz et al., "Visualization of Surfactants on Nanostructured Palladium Clusters by a Combination of STM and High-Resolution TEM," <i>Science</i> , Vol. 267 (1995), pp. 367-369.
	*	F. Meldrum et al., "Formation of Thin Films of Platinum, Palladium, and Mixed Platinum: Palladium Nano-crystallites by the Langmuir Monolayer Technique," <i>Chem. Mater.</i> 7 (1995), pp. 1112-1116.
NOV	*	T. Vargo et al., "Adhesive Electroless Metallization of Fluoropolymeric Substrates," <i>Science</i> , Vol. 262 (1993), pp. 1711-1712.

* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. _____, filed _____, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

Examiner

M. Vargo

DATE CONSIDERED

12/22/06

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.



FORM PTO-1449(Modified)	DOCKET NO. H0498.70114US01		SERIAL NO. 10/677,103
	APPLICANTS: Enoch Kim et al.		
	FILING DATE 10/01/2003		GROUP ART UNIT: 1732

OTHER ART

(Including Author, Title, Date, Pertinent Pages, Publication, Etc.)

MOV	*	J. Calvert et al., "Deep ultraviolet patterning of monolayer films for high resolution lithography," <i>J. Vac. Sci. Technol. B9</i> (6) (1991), pp. 3447-3450.
A		J. Li et al., "Copper-Based Metallization for ULSI Applications," <i>MRS Bulletin</i> , (1993), pp. 18-21.
	*	J. Chou et al., "Electroless Cu for VLSI", <i>MRS Bulletin</i> (1993), pp. 31-37.
	*	A. van der Putten et al., "Electrochemistry of Colloidal Palladium," <i>J. Electrochem. Soc.</i> , Vol. 139, No. 12 (1992) pp. 3475-3480.
	*	C. Ting et al., "Selective Electroless Metal Deposition of Integrated Circuit Fabrication," <i>J. Electrochem. Soc.</i> , Vol. 136, No. 2, (1989), pp. 456-462.
	*	R. Jackson, "Pd+2/Poly(acrylic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation," <i>J. Electrochem. Soc.</i> , Vol. 137, No. 1, (1990), pp. 95-101.
	*	A. van der Putten et al., "Anisotropic Deposition of Electroless Nickel," <i>J. Electrochem. Soc.</i> , Vol. 140, No. 8 (1993), pp. 2229-2235.
	*	A. van der Putten, "Controlled Mechanical Adhesion of Electroless Cu Patterns," <i>J. Electrochem. Soc.</i> , Vol. 140 No. 8, (1993), pp. 2376-2378.
	*	R. Jackson, "Initiation of Electroless Copper Plating Using Pd+2/Poly(acrylic acid) Films," <i>J. Electrochem. Soc.</i> (1998), pp. 3172-3173.
	*	C. Mak, "Electroless Copper Deposition on Metals and Metal Silicides," <i>MRS Bulletin</i> , (1994), pp. 55-62.
	*	W. Dressick et al., "Photopatterning and Selective Electroless Metallization of Surface-Attached Ligands," <i>J. Chem. Mater.</i> 5, (1993), pp. 148-150.
	*	S. Nakahara et al., "Microstructure and Mechanical Properties of Electroless Copper Deposits," <i>Annu. Rev. Mater. Sci.</i> 21, (1991), pp. 93-129.
	*	N. Jeon et al., "Patterned Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates," <i>Langmuir</i> 11 (1995), pp. 3204-3206.
MOV	*	V. Dubin, "Electroless Ni-P Deposition on Silicon with Pd Activation," <i>J. Electrochem. Soc.</i> , Vol. 139, No. 5, May, 1992, pps. 1289-1294.

* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. _____, filed _____, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

Examiner <i>M. Vargus</i>	DATE CONSIDERED <i>12/22/06</i>
---------------------------	---------------------------------

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.



FORM PTO-1449 (modified PTO/SB/08) INFORMATION DISCLOSURE STATEMENT BY APPLICANT				APPLICATION NO.: 10/677103		ATTY. DOCKET NO.: H0498.70114US01	
				FILING DATE: October 1, 2003		CONFIRMATION NO.: 4302	
				APPLICANT: Enoch Kim et al.			
				GROUP ART UNIT: 1732		EXAMINER: Not Yet Assigned	
Sheet	1	of	1				

U.S. PATENT DOCUMENTS

Examiner's Initials #	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication or Issue of Cited Document MM-DD-YYYY
		Number	Kind Code		
MDV		6,766,817	V2	da Silva	07-27-2004

FOREIGN PATENT DOCUMENTS

Examiner's Initials #	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Translation (Y/N)
		Office/ Country	Number	Kind Code			

OTHER ART — NON PATENT LITERATURE DOCUMENTS

Examiner's Initials #	Cite No	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	Translation (Y/N)

EXAMINER: <i>M. Vagot</i>	DATE CONSIDERED: <i>12/22/06</i>
------------------------------	-------------------------------------

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. __, filed __, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

[NOTE — No copies of U.S. patents, published U.S. patent applications, or pending, unpublished patent applications stored in the USPTO's Image File Wrapper (IFW) system, are included. See 37 CFR §1.98 and 1287OG163. Copies of all other patent(s), publication(s), unpublished, pending U.S. patent applications, or other information listed are provided as required by 37 CFR §1.98 unless 1) such copies were provided in an IDS in an earlier application that complies with 37 CFR §1.98, and 2) the earlier application is relied upon for an earlier filing date under 35 U.S.C. §120.]